

Chip Inductors Type KL32 Series

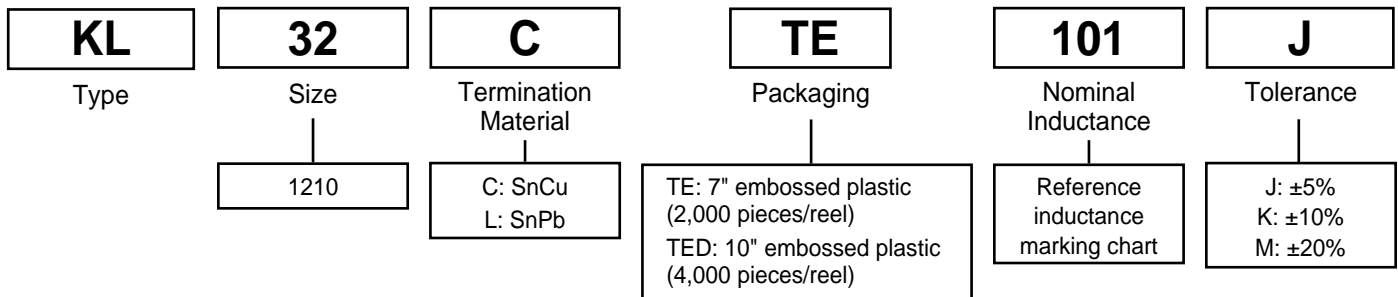
ISO 9001:2000
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1. Scope

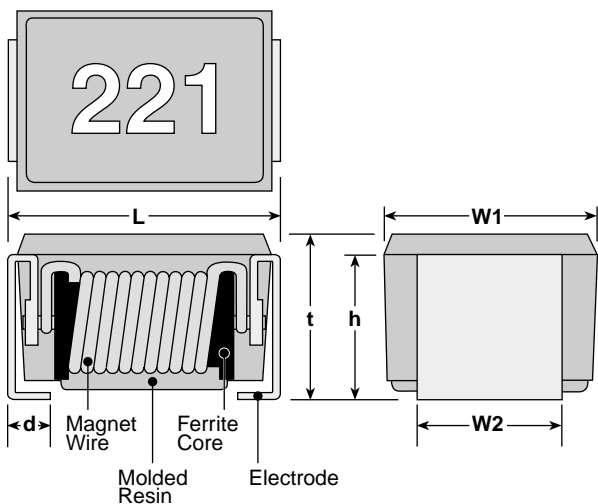
This specification applies to Chip Inductors (KL32) produced by KOA Corporation.

2. Type Designation

The type designation shall be the following form:



3. Dimensions and Construction



Type	Dimensions inches (mm)					
	L	W1	W2	t	h	d
KL32	.126±.008 (3.2±0.2)	.098±.008 (2.5±0.2)	.067±.004 (1.7±0.1)	.087±.008 (2.2±0.2)	.075±.004 (1.9±0.1)	.02 nominal (.5 nominal)

Inductance Marking

Value	Code
0.005µH - 0.082µH	005 - 082
0.10µH - 8.2µH	R10 - 8R2 R indicates decimal point.
10µH - 330µH	100 - 331 1st two figures are significant, the last figure indicates the number of zeros to follow.

4. Standard Applications

Part Designation	Inductance (µH)	Inductance Tolerance	Quality Factor Minimum	Self Resonant Frequency Minimum (MHz)	DC Resistance Maximum (Ω)	Allowable DC Current Maximum (mA)	Measured Frequency (MHz)	
KL32*TE005**	0.005	M: ±20%	11	2700	0.12	450	100	
KL32*TE010**	0.010	K: ±10% M: ±20%	15	2500	0.13			
KL32*TE012**	0.012		17	2300	0.14			
KL32*TE015**	0.015		19	2100	0.16			
KL32*TE018**	0.018		21	1900	0.18			
KL32*TE022**	0.022		23	1700	0.20			
KL32*TE027**	0.027		23	1500	0.22			
KL32*TE033**	0.033	J: ±5% K: ±10% M: ±20%	25	1400	0.24			
KL32*TE039**	0.039			1300	0.27			
KL32*TE047**	0.047		26	1200	0.30			
KL32*TE056**	0.056			1100	0.33			
KL32*TE068**	0.068		27	1000	0.36			
KL32*TE082**	0.082			900	0.40			
KL32*TER10**	0.10		J: ±5% K: ±10% M: ±20%	28	700			0.44
KL32*TER12**	0.12				500	0.22		
KL32*TER15**	0.15			450	0.25			
KL32*TER18**	0.18			400	0.28			
KL32*TER22**	0.22			350	0.32			
KL32*TER27**	0.27			320	0.36			
KL32*TER33**	0.33	300		0.40				
KL32*TER39**	0.39	250		0.45				
KL32*TER47**	0.47	220		0.50				
KL32*TER56**	0.56	180		0.55				
KL32*TER68**	0.68	160		0.60				
KL32*TER82**	0.82	140		0.65				
KL32*TE1R0**	1.0	J: ±5% K: ±10% M: ±20%		30	120	0.70	400	7.96
KL32*TE1R2**	1.2				100	0.75	390	
KL32*TE1R5**	1.5		85		0.85	370		
KL32*TE1R8**	1.8		80		0.90	350		
KL32*TE2R2**	2.2		75		1.0	320		
KL32*TE2R7**	2.7		70		1.1	290		
KL32*TE3R3**	3.3		60		1.2	260		
KL32*TE3R9**	3.9		55		1.3	250		
KL32*TE4R7**	4.7		50		1.5	220		
KL32*TE5R6**	5.6		47		1.6	200		
KL32*TE6R8**	6.8		43		1.8	180		
KL32*TE8R2**	8.2		40		2.0	170		
KL32*TE100**	10		36		2.1	150		
KL32*TE120**	12		33		2.5	140		
KL32*TE150**	15		30	2.8	130			
KL32*TE180**	18		27	3.3	120			
KL32*TE220**	22		25	3.7	110			
KL32*TE270**	27		20	5.0	80			
KL32*TE330**	33		17	5.6	70			
KL32*TE390**	39		16	6.4	65			
KL32*TE470**	47		15	7.0	60			
KL32*TE560**	56		13	8.0	55			
KL32*TE680**	68		12	9.0	50			
KL32*TE820**	82		11	10	45			
KL32*TE101**	100		20	10	10	40	50	0.796
KL32*TE121**	120				11	70		
KL32*TE151**	150			8	15	65		
KL32*TE181**	180			7	17	60		
KL32*TE221**	220			7	21	60		
KL32*TE271**	270			6	28	50		
KL32*TE331**	330	5		34	50			

* Add termination material character (C, L)

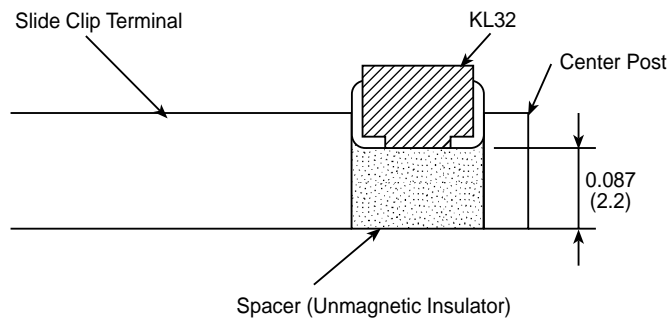
** Add tolerance character (J, K, M)

5. Measurement Method of L and Q

Nominal Inductance Range (μH)	Measurement Method	Measuring Frequency (MHz)
0.005 ~ 0.10	Please see Method-1	100
0.12 ~ 0.82		25.2
1.0 ~ 8.2		7.96
10 ~ 82	Please see Method-2	2.52
100 ~ 330		0.796

Method-1

Test Equipment: Hewlett Packard RF Impedance analyzer 4191A
 Fixture: Hewlett Packard Spring clip fixture 16092A
 Electrical Length: 2.10 cm
 Setting: Please see the following figure



Method-2

Test Equipment: Hewlett Packard LF Impedance analyzer 4192
 Fixture: Hewlett Packard Test fixture 16034E
 OSC Level: 0.3 V

6. Test Condition

Unless otherwise specified, the test shall be performed in accordance with JIS-C-5202 specifying marking measurements as follows:

Ambient temperature: $20 \pm 15^\circ\text{C}$
 Relative humidity: $65 \pm 20\%$

If there may be any doubt on results, measurements shall be made within the following limits:

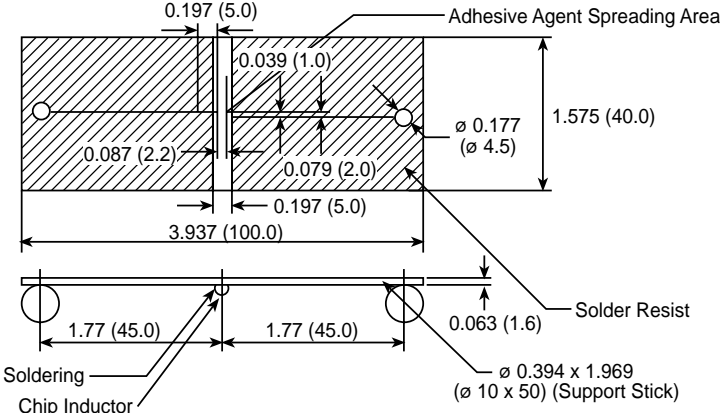
Ambient temperature: $20 \pm 2^\circ\text{C}$
 Relative humidity: $65 \pm 5\%$

7. Reliability Data

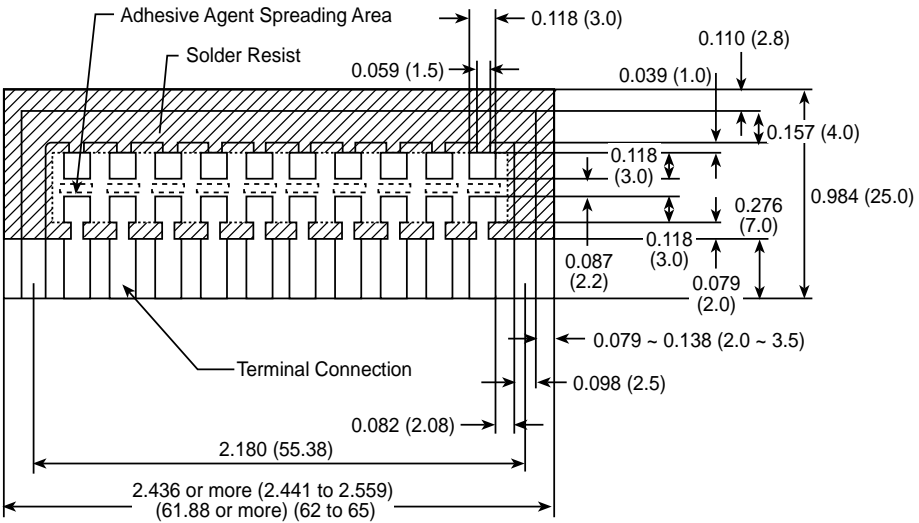
7-1 Electrical Characteristics

Item	Requirement	Test Method
DC Bias Characteristic	$\Delta L/L$: Within - 10%	Measure inductance with application of rated current using LCR meter to compare it with the initial value.
Dielectric Withstanding Voltage	No fuming, flaming, or breakdown	5 seconds at DC 1000V between terminal 1 (one electrode of inductor) and terminal 2 (the thin copper wire which is wound around the inductor more than twice).
Insulation Resistance	More than 1000M Ω	Measure resistance immediately after 1 minute passed since DC 500V was applied between terminal 1 and 2.

7-2 Mechanical Characteristics

Item	Requirement	Test Method
Terminal Pull Strength	No damage	Terminals shall withstand a pull of 0.5kgf in a horizontal direction.
Terminal Bending Strength	No damage	Specimen shall be soldered on PCB-A (see figure below) and support by applying strength so that the bending width becomes 10 mm.
Thickness: 1.6 mm Material: Paper Phenol (a) Board (b) Install Units: inches (mm)		

7-2 Mechanical Characteristics *Continued*

Item	Requirement	Test Method
Vibration	No significant abnormality in appearance $\Delta L/L$: Within $\pm 3\%$	2 hours in each X, Y and Z directions on PCB-B (see figure below) at a frequency range of 10 to 55 to 10 Hz (1 min.) with 1.5 mm amplitude.
<p>Thickness: 1.6 mm Material: Glass Epoxy</p>  <p>Units: inches (mm)</p>		
Resistance to Solder Heat	No significant abnormality in appearance $\Delta L/L$: Within $\pm 3\%$	Immerse in the solder (H63A) of $260 \pm 5^\circ\text{C}$ for 10 ± 1 sec.
Solderability	Over 95% of electrode surface shall be covered with solder	Immerse in the solder (H63A) of $230 \pm 5^\circ\text{C}$ for 3 ± 0.5 sec.
Drop Test	No significant abnormality in appearance $\Delta L/L$: Within $\pm 3\%$	Drop from a height of 1 m to the ground of concrete or tile 1 time.

7-3 Environmental Characteristics *

Item	Requirement	Test Method
Low Temperature Life Test	Δ L/L: Within $\pm 5\%$ Δ Q/Q: Within $\pm 20\%$	Store at $-40 \pm 2^\circ\text{C}$ for 1000 hours.
High Temperature Life Test	Δ L/L: Within $\pm 5\%$ Δ Q/Q: Within $\pm 30\%$	Store at $100 \pm 2^\circ\text{C}$ for 1000 hours.
Thermal Shock	Δ L/L: Within $\pm 5\%$	100 cycles between $-25 \pm 2^\circ\text{C}$ / 1 hour and $+100 \pm 2^\circ\text{C}$.
Temperature Characteristic	Δ L/L: Within $\pm 10\%$	Measure Δ L/L at the temperature of between -25°C and $+100^\circ\text{C}$ as based on the temperature of 20°C .
Humidity	Δ L/L: Within $\pm 5\%$ Δ Q/Q: Within $\pm 30\%$	Store at $40 \pm 2^\circ\text{C}$, 90 to 95% RH for 1000 hours.
Humidity Loading Test	Δ L/L: Within $\pm 5\%$ Δ Q/Q: Within $\pm 30\%$	Apply rated current continuously at $40 \pm 2^\circ\text{C}$, 90 to 95% RH for 1000 hours.
High Temperature Loading Test	Δ L/L: Within $\pm 5\%$ Δ Q/Q: Within $\pm 30\%$	Apply rated current continuously at $100 \pm 2^\circ\text{C}$ for 1000 hours.
Solvent Resistance	No outstanding damage and markings can be easily judged	According to MIL-STD-202F Method 215 (1990).
Storage Temperature Range	-40°C to $+100^\circ\text{C}$	—
Operating Temperature Range	-40°C to $+100^\circ\text{C}$	—

* Unless otherwise specified, at least one hour of recovery under the normal temperature and normal humidity after the test, followed by the measurement within two hours.

8. Packaging

8-1 Taping

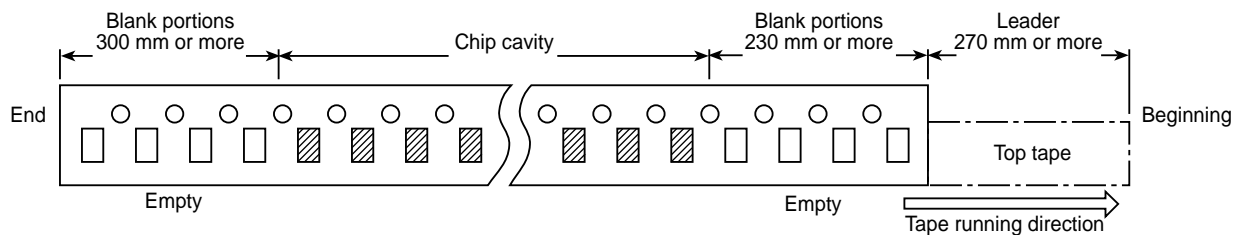
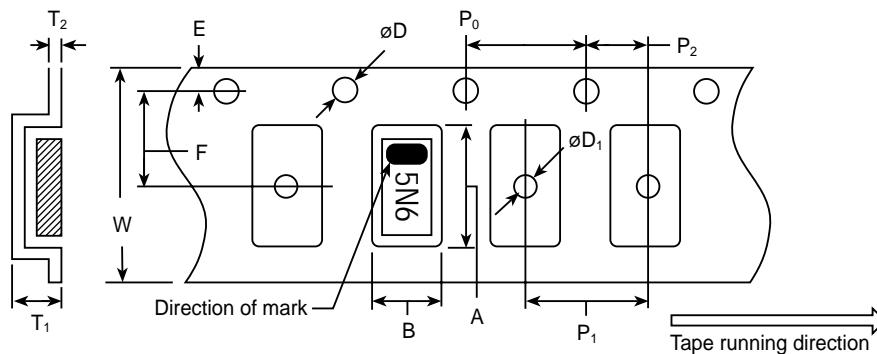
The tapes for taping shall be embossed carrier tapes of .315" (8 mm) width and .157" (4 mm) pitch. The standard quantity per reel shall be 2,000 pieces.

(1) Dimensions of carrier tape Dimensions in inches (mm)

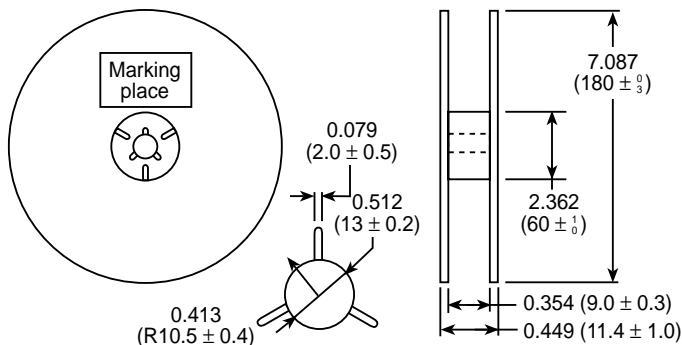
A	.140 (3.55 ± 0.10)	T₂	.011 (0.28 ± 0.05)
B	.106 (2.70 ± 0.10)	P₀	.157 (4.00 ± 0.10)
W	.315 (8.00 ± 0.10)	P₁	.157 (4.00 ± 0.10)
E	.069 (1.75 ± 0.10)	P₂	.079 (2.00 ± 0.05)
F	.138 (3.50 ± 0.05)	∅D*	.059 (1.50 ± ^{0.1} ₀)
T₁	.106 (2.70 ± 0.15)	∅D₁	.039 (1.00 ± ^{0.2} ₀)

The top tape requires a peel-off force of 15 to 60 gf.

* 20 pitches accumulation of sprocket holes shall be 80.00 ± 0.15 mm.



(2) Reel dimensions



Dimensions in inches (mm)

(Marking item)

- (1) Type designation
- (2) Nominal inductance and tolerance
- (3) Quantity
- (4) Production lot number
- (5) Manufacturer's name

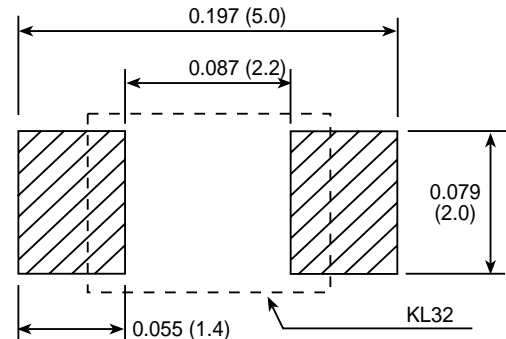
9. Recommended Soldering Condition

9-1 Dimensions of Standard Land

The following figure is recommended land dimensions.

When two or more chip inductors are closely mounted, they must be separated by means of solder resists to prevent excessive solder.

Dimensions in inches (mm)

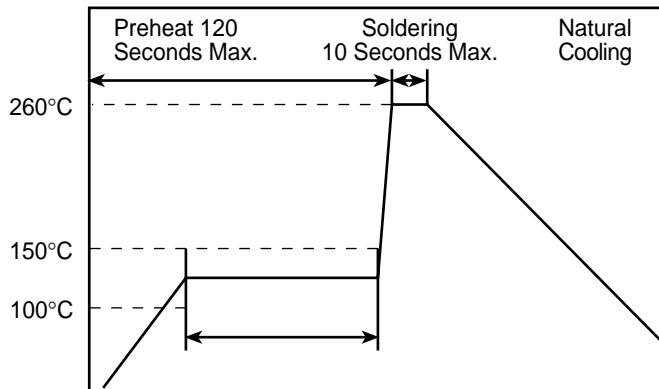


9-2 Soldering Condition

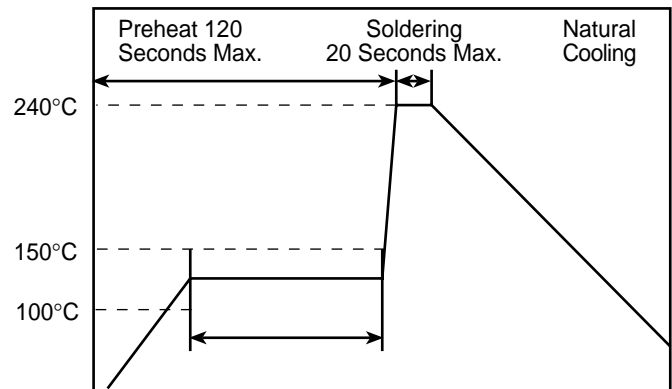
Wave soldering should be done at 260°C for less than 10 seconds. Reflow soldering should be done at 240°C for less than 20 seconds. (Please see the following figures.)

When using a soldering iron, temperature shall not exceed 350°C and within three seconds. Soldering iron time shall be allowed only one time. After soldering, chip inductors shall not be stressed excessively.

Recommended Temperature Profile for Wave Soldering



Recommended Temperature Profile for Reflow Soldering



10. Mounting

Placement force should not be excessive.

11. Recommended Washing Condition

Since this chip inductor is a coil of ultra-thin wire, it is susceptible to vibration.

If an ultrasonic cleaning unit is used for cleaning, check for any possibility of problem generation before practical use since such cleaning units considerably differ in vibration level and mode. Although the conditions differ depending on the printed board size, ultrasonic cleaning is generally used in the conditions described below as examples:

- Ultrasonic power: Within 20W/1
- Cleaning times: Within 5 minutes

12. Storage

Chip inductors should not be stored under high temperature and high humidity conditions. In particular, do not store **taping** where it is exposed to heat or direct sunlight. Otherwise, the packing material may be deformed, causing problems during mounting.